

RECEIVED
CENTRAL FAX CENTER

Output Date: 8/9/2004

SEP 09 2004

Dispatch Number: 9-5-2004-032163881
Dispatch Date: August 5, 2004
Submission Deadline: October 5, 2004

To: Jong-han Pak, Dong-Yol Yoon International
Patent & Law Firm
#901 Ryeosam Building, 648-23
Yeoksam-dong, Gangnam-gu, Seoul 135-748

[Stamp: Receipt, 8/9/2004, No. 1114, Dong-Yol Yoon International Patent & Law Firm]

KOREAN INTELLECTUAL PROPERTY OFFICE
NOTIFICATION OF OPINION

Applicant: Name: Murata Manufacturing Co., Ltd. (Applicant Code: 519980960646)
Address: 26-10, Denjin 2nd Street, Nakaokakyo, Kyoto, Japan

Agent: Name: Jong-han Pak and two others
Address: Dong-Yol Yoon International Patent & Law Firm, #901 Ryeosam Building,
648-23 Yeoksam-dong, Gangnam-gu, Seoul

Application Number: 10-2001-0054418

Title of Invention: Method of Adjusting Frequency Characteristics of Single Surface Reflection-type Surface Wave Device and Method of Manufacturing Single Surface Reflection-type Surface Wave Device

This is to inform you, pursuant to Article 63 of the Patent Act, that a review of this patent application resulted in the following grounds for rejection. If you have an opinion regarding this or if the application requires correction, please submit a written statement of opinion (Accompanying Document Form No. 25-2 of the Enforcement Regulation of the Patent Act) and/or an amendment (Accompanying Document Form No. 5 of the Enforcement Regulation of the Patent Act) by the deadline above. (Applications for extension of the deadline above may be filed for one month at a time. No separate extension approved notification is provided regarding such an application.)

(Grounds for Rejection)

The inventions described in all claims of this application are unpatentable pursuant to Article 29 (2) of the Patent Act because, prior to this application, a person with an ordinary knowledge of the technical field to which these inventions belong could create the inventions easily based on the information provided below.

1. The inventions described in all of the claims of this application relate to a method of adjusting the frequency characteristics of a surface wave device and a method of manufacturing a surface wave device. First, the inventions described in Claim 1 through Claim 7 of this application, relating to a method of adjusting the frequency characteristics of a surface wave device containing a piezoelectric substrate and IDTs, comprise a phase in which the frequency characteristics are measured, and a phase in which the piezoelectric substrate is cut according to the frequency characteristics, etc. However, these inventions could easily be created by a person with an ordinary knowledge of the technical field to which these inventions belong by combining Cited Invention 1 (Japan Patent Laid-Open H8-48467), which relates to a method of adjusting the frequency of an elastic surface wave filter comprising a piezoelectric substrate and IDTs, etc., wherein the frequency is measured and etching is performed based on the result, and Cited Invention 2 (Japan Patent Laid-Open H12-156620), which relates to a method of adjusting the core frequency of an elastic surface wave device and a method of manufacturing an elastic surface wave device, wherein an elastic surface wave device is manufactured on the piezoelectric substrate, the frequency characteristics are measured, and etching is performed. Furthermore, the inventions described in Claims 8 through Claim 15 of this application, relating to a method of manufacturing a surface wave device, comprise a phase in which IDTs are formed, a substrate is cut, a surface wave device is manufactured, and the frequency characteristics are measured, wherein the position of a single surface is determined based on the measured frequency characteristics. However, these inventions could easily be created by a person with an ordinary knowledge of the technical field to which these inventions belong by combining Cited Invention 2 characterized by a similar purpose and method (composition) and Cited Invention 3 (Japan Patent Laid-Open H9-186553), which relates to an elastic surface wave device and a method of its manufacturing, comprising a piezoelectric substrate, and IDTs, etc., wherein the composition is made based on the frequency characteristics.

2-1

Output Date: 8/9/2004

[Attachment]

Attachment 1. Cited Invention 1: Japan Laid-Open Patent H08-046467 (02. 16. 1996), 1 copy

Attachment 2. Cited Invention 2: Japan Laid-Open Patent H12-156620 (06. 06. 2000), 1 copy

Attachment 3. Cited Invention 3: Japan Laid-Open Patent H09-186553 (07. 15. 1997), 1 copy End.

August 6, 2004

Korean Intellectual Property Office Electricity & Electronics Examination Bureau
Electronics Examiners' Office Examiner: Kim Jae-mun [seal]

<<Information>>

Should you have any questions, please call 042-481-5673.
All Korean Intellectual Property Office employees are doing their best to achieve clean patent administration. Please report any employee misconduct you may encounter. Corruption Reporting Center on KIPO's home page (www.kipo.go.kr)